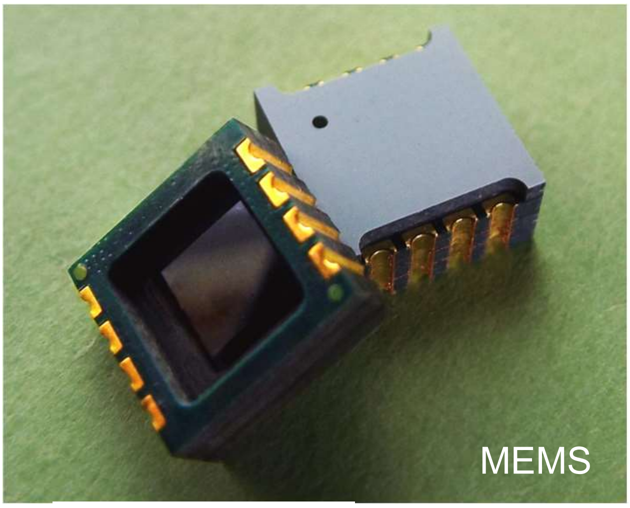
Sensor Packaging

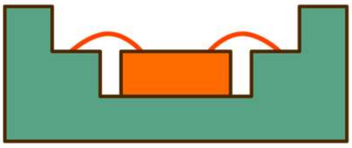
MEMS sensors and image sensors

For IoT, wearable devices and automotive electronics, we provide advanced sensor packages synergized by our processing technologies and material knowledge.



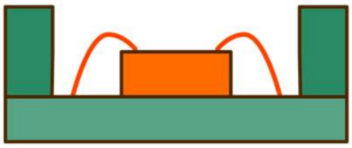
Cavity

High reliability by milled structure inserting IC chip on cavity structure in resin substrate.



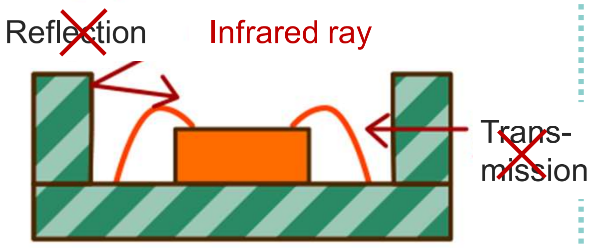
Lamination

Cavity structure to laminate frame plate on base substrate.



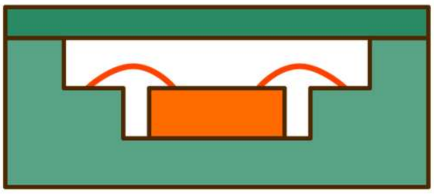
Infrared insulation

Prevents sensors malfunction and decreasing sensitivity by cutting reflection or transmission of light



MEMS

Mounting chip on resin substrate and laminate lid to make hollow package.



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